

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	TAKAHIRO HATTORI	11/13/2014
	DAISUKE SOMA	11/13/2014
	ISAMU SATO	11/13/2014
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PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	14475249	
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DATE SIGNED:	12/01/2014	
Total Attachments: 1		
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ASSIGNMENT - PATENT APPLICATION

WHEREAS, I/We, Takahiro HATTORI, Daisuke SOMA, and Isamu SATO have invented certain new and useful improvements in an invention entitled

**Bump Electrode, Board Which Has Bump Electrodes,
and Method for Manufacturing the Board,**

which is the subject of pending United States Patent Application Serial No. 14/475,249 filed September 2, 2014, claiming priority to Japanese Patent application No. 2013-182296 filed September 3, 2013; and

WHEREAS, Senju Metal Industry Co., Ltd. of 23, Senju-Hashido-cho, Adachi-ku, Tokyo 120-8555, JAPAN (hereinafter "Assignee") desires to acquire an interest in said improvements and in the Letters Patent to be obtained therefor;

NOW THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are acknowledged, I/We hereby assign and transfer to Assignee, for the territory of the United States of America and all other countries, the entire right, title, and interest in and to said improvements and in and to said application and any Letters Patent that may be granted therefor in the United States and any other country including any division, continuation, substitute, renewal or reissue of said application or said Letters Patent.

I/We hereby agree to communicate to Assignee any facts known to me/us relating to said improvements, to testify as to the same in any interference or legal proceeding concerned therewith, to execute promptly and deliver to Assignee upon request any and all papers, instruments, declarations and affidavits required to apply for, obtain, maintain and enforce said Letters Patent, and generally to do everything necessary or desirable to vest and perfect title thereto in Assignees.

This assignment is binding upon me/us and my/our heirs, successors, and legal representatives, and shall inure to the benefit of Assignee and its successors, assigns and nominees.

INVENTOR(S):

Takahiro Hattori

Takahiro HATTORI

November 13, 2014

Date

Daisuke Soma

Daisuke SOMA

November 13, 2014

Date

ISAMU SATO

Isamu SATO

November 13, 2014

Date